



非接触3次元測定S/Wツール
Non-contact 3D Measurement S/W Tool

垂直方向0.5nmの高精度
High accuracy of 0.5nm vertically

優れた繰り返し精度と再現性
Excellent repeatability and reproducibility

表面解析 WSI 3D高精度光学モジュールを搭載 ウエハパターンの高精度・高速測定に最適

Equipped with surface analysis WSI 3D high-precision optical module.
Suitable for high-precision and high-speed measurement of wafer patterns

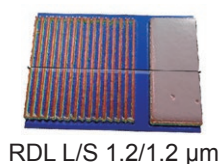
主要機能 | Main Functions

- ▶ Roughness
- ▶ Ra, Rq, Rz, Rvk, Sdr...
- ▶ RDL thickness, width L/S/H = 2um/2um/3um
Next = 1.4um/1.4um/3um
- ▶ Film thickness
- ▶ PI and PR film thickness and open
- ▶ Plated Cu thickness
- ▶ CD of UBM (Large UBM Size : $\phi 300\mu\text{m}$)
- ▶ Copper pillars height, diameter, and pitch
- ▶ Overlay
- ▶ Full Die Stitching → Waviness and Form
- ▶ Depth and top CD
- Etc..

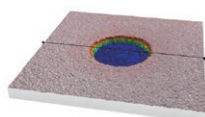
仕様 | Specifications

Model	NSW-300B	NSW-300T	NSW-300H	NSW-350E
RDL	●	●	●	●
UBM	●	●	●	●
Overlay	●	●	●	●
Bump	●	●	●	●
PI, PR Thickness	—	●	●	●
Thick Film	—	●	●	●
Large area Thickness	—	●	●	●
High Aspect Ratio Trench	—	—	●	●
Dicing Depth Width	—	—	●	●
Wafer Bow	—	—	—	●

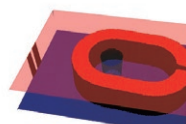
測定機能 | Measuring Items



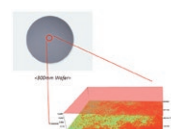
RDL L/S 1.2/1.2 μm



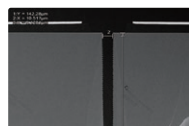
Via hole



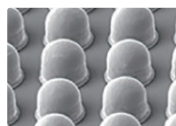
Overlay



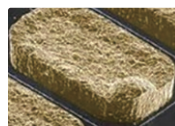
Thin film measurement



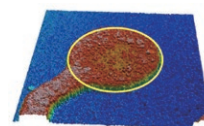
High Aspect Ratio



Cu pillar



Gold bump



Pad